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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c57-lpi-ss

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

NOTES:

PIC16C5X



FIGURE 5-4: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): FAST VDD RISE TIME



FIGURE 5-5: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): SLOW VDD RISE TIME



CONFIGURATION WORD FOR PIC16C54/C55/C56/C57 **REGISTER 9-2:**

—	—	—	—	—	—	—	—	CP	WDTE	FOSC1	FOSC0
bit 11											bit 0
bit 11-4:	Unimple	emented:	Read as '	0'							
bit 3:	CP: Cod 1 = Cod 0 = Code	le protecti de protecti e protectio	on bit. on off on on								
bit 2:	WDTE:	Watchdog	timer ena	ble bit							
	1 = WD7	T enabled									
	0 = VVD	I disabled			. (2)						
bit 1-0:	FOSC1:	FOSC0: (Oscillator s	election b	oits ⁽²⁾						
	00 = L	P oscillato	or								
	01 = X	I oscillato	or								
	$10 = \Pi$	C oscillat) or								
	TT = K		JI								
Note 1:	Refer to	the PIC16	C5X Prog	ramming	Specificat	ions (Liter	ature Nun	nber DS30	0190) to d	etermine h	now to
	access th	he configu	ration wor	d.							
2:	PIC16LV	/54A supp	orts XT, R	C and LP	oscillator	only.					
L a sua a du											

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ad as '0'
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown

ADDWF	Add	W	and f			
Syntax:	[lab	[label]ADDWF f,d				
Operands:	$0 \le 1$ $d \in 1$	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$				
Operation:	(W)	+ (f)	\rightarrow (dest)			
Status Affected:	C, D	C, Z				
Encoding:	00	01	11df	ff	ff	
	and is st '1' th regi	regi ored ne re ister	ster 'f'. If 'o I in the W sult is sto 'f'.	d' is regi red	0 the ster. I back	result If 'd' is in
Words:	1					
Cycles:	1					
Example:	ADD	WF	TEMP_RE	G,	0	
Before Instr	uctio	n				
W		=	0x17			
TEMP_I After Instruc	REG ction	=	0xC2			
W		=	0xD9			
TEMP_F	REG	=	0xC2			

ANDWF	AND W with f
Syntax:	[label] ANDWF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$
Operation:	(W) .AND. (f) \rightarrow (dest)
Status Affected:	Ζ
Encoding:	0001 01df ffff
Description:	The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W regis- ter. If 'd' is '1' the result is stored back in register 'f'.
Words:	1
Cycles:	1
Example:	ANDWF TEMP_REG, 1
Before Instru W TEMP_I After Instruct W TEMP_I	action = $0x17$ REG = $0xC2$ ion = $0x17$ REG = $0x02$

ANDLW	AND literal with W				
Syntax:	[<i>label</i>] ANDLW k				
Operands:	$0 \le k \le 255$				
Operation:	(W).AND. (k) \rightarrow (W)				
Status Affected:	Z				
Encoding:	1110 kkkk kkkk				
Description:	The contents of the W register are AND'ed with the eight-bit literal 'k'. The result is placed in the W regis- ter.				
Words:	1				
Cycles:	1				
Example:	ANDLW H'5F'				
Before Instru W = After Instruct W =	ction 0xA3 ion 0x03				

BCF	Bit Clea	rf			
Syntax:	[label] BCF f,b				
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$				
Operation:	$0 \rightarrow (f < b >)$				
Status Affected:	None				
Encoding:	0100	bbbf	ffff		
Description:	Bit 'b' in	register 'f'	is cleare	d.	
Words:	1				
Cycles:	1				
Example:	BCF	FLAG_RE	G, 7		
Before Instru FLAG_R After Instruct	ction EG = ion	0xC7			
FLAG_R	EG =	0x47			

BSF	Bit Set f					
Syntax:	[label]	[label] BSF f,b				
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$					
Operation:	$1 \rightarrow (f < b >)$					
Status Affected:	None					
Encoding:	0101	bbbf	ffff			
Description:	Bit 'b' in r	register 'f'	is set.			
Words:	1					
Cycles:	1					
Example:	BSF	FLAG_RE	G, 7			
Before Instruction FLAG_REG = 0x0A After Instruction						
$FLAG_REG = 0x8A$						

BTFSC	Bit Test f, Skip if Clear					
Syntax:	[label]	BTFSC	f,b			
Operands:	$\begin{array}{l} 0 \leq f \leq 3 \\ 0 \leq b \leq 7 \end{array}$	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$				
Operation:	skip if (f) = 0				
Status Affected:	None					
Encoding:	0110	bbbf	ffff			
Description:	If bit 'b' in register 'f' is 0 then the next instruction is skipped. If bit 'b' is 0 then the next instruc- tion fetched during the current instruction execution is discarded, and a NOP is executed instead, making this a 2-cycle instruction					
Words:	1					
Cycles:	1(2)					
Example:	HERE FALSE TRUE	BTFSC GOTO • •	FLAG,1 PROCESS	S_CODE		
Before Instru	ction					
PC After Instructi if FLAG< PC if FLAG< PC	= (1> = (1> = (1> = =	address 0, address (1, address (1	(HERE) TRUE); FALSE)			

BTFSS	Bit Test f, Skip if Set					
Syntax:	[label] BTFSS f,b					
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b < 7 \end{array}$					
Operation:	skip if (f) = 1					
Status Affected:	None					
Encoding:	0111 bbbf ffff					
Description:	If bit 'b' in register 'f' is '1' then the next instruction is skipped. If bit 'b' is '1', then the next instruc- tion fetched during the current instruction execution, is discarded and a NOP is executed instead, making this a 2-cycle instruction.					
Words:	1					
Cycles:	1(2)					
Example:	HERE BTFSS FLAG,1 FALSE GOTO PROCESS_CODI TRUE • •	Ξ				
Before Instr	ruction					
PC	= address (HERE)					
After Instruc	ction					
	< i > = 0, = address (FALSE)					
if FLAG<	<1> = 1.					
PC	= address (TRUE)					

GOTO	Uncondi	tional Br	anch	
Syntax:	[label]	GOTO	k	
Operands:	$0 \le k \le 5^{-1}$	11		
Operation:	$k \rightarrow PC < 8:0>;$ STATUS<6:5> $\rightarrow PC < 10:9>$			
Status Affected:	None			
Encoding:	101k	kkkk	kkkk	
Description:	GOTO is a The 9-bit loaded in upper bits STATUS- cycle inst	an uncone immedia to PC bit s of PC a <6:5>. GC truction.	ditional branch. te value is s <8:0>. The re loaded from DTO is a two-	
Words:	1			
Cycles:	2			
Example:	GOTO TH	IERE		
After Instructi PC =	on address	G (THER	E)	

INCF	Increment f
Syntax:	[label] INCF f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in [0,1] \end{array}$
Operation:	(f) + 1 \rightarrow (dest)
Status Affected:	Z
Encoding:	0010 10df ffff
Description:	The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words:	1
Cycles:	1
Example:	INCF CNT, 1
Before Instru CNT Z After Instructi CNT Z	ction = 0xFF = 0 ion = 0x00 = 1

INCFSZ	Increment f, Skip if 0					
Syntax:	[label] INCFSZ f,d					
Operands:	$\begin{array}{l} 0\leq f\leq 31\\ d\in [0,1] \end{array}$					
Operation:	(f) + 1 \rightarrow (dest), skip if result = 0					
Status Affected:	None					
Encoding:	0011 11df ffff					
Description:	The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. If the result is 0, then the next instruction, which is already fetched, is discarded and a NOP is executed instead making it a two-					
Words:	1					
Cycles:	1(2)					
Example:	HERE INCFSZ CNT, 1 GOTO LOOP					
	CONTINUE • • •					
Before Instru	iction					
PC	= address (HERE)					
After Instruct	ion					
CNT	= CNT + 1;					
if CNT	= 0,					
PC	= address (CONTINUE);					
if CNT	≠ 0, 					
PC	= address (HERE +1)					

12.2 DC Characteristics: PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)				Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial				
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions	
D001	Vdd	Supply Voltage PIC16C5X-RCI PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-HSI	3.0 3.0 4.5 4.5		6.25 6.25 5.5 5.5 6.25	V V V V		
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	2.5	1.5*		V	Device in SLEEP mode	
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset	
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset	
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RCI ⁽³⁾ PIC16C5X-XTI PIC16C5X-10I PIC16C5X-HSI PIC16C5X-HSI PIC16C5X-LPI		1.8 1.8 4.8 9.0 15	3.3 3.3 10 10 20 40	mA mA mA mA μA	Fosc = 4 MHz, VDD = $5.5V$ Fosc = 4 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 20 MHz, VDD = $5.5V$ Fosc = 32 kHz, VDD = $3.0V$, WDT disabled	
D020	IPD	Power-down Current ⁽²⁾	_	4.0 0.6	14 12	μΑ μΑ	VDD = 3.0V, WDT enabled VDD = 3.0V, WDT disabled	

* These parameters are characterized but not tested.

- † Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

AC Chara	cteristics	$\begin{array}{llllllllllllllllllllllllllllllllllll$							
Param No.	Symbol	Characteristic Min Typ† Max Units Conditio							
1	Tosc	External CLKIN Period ⁽¹⁾	250			ns	XT OSC mode		
			100		—	ns	10 MHz mode		
			50		—	ns	HS OSC mode (Comm/Ind)		
			62.5		—	ns	HS OSC mode (Ext)		
			25		—	μS	LP OSC mode		
		Oscillator Period ⁽¹⁾	250	—	—	ns	RC OSC mode		
			250		10,000	ns	XT OSC mode		
			100		250	ns	10 MHz mode		
			50		250	ns	HS OSC mode (Comm/Ind)		
			62.5		250	ns	HS OSC mode (Ext)		
			25		—	μS	LP OSC mode		
2	Тсу	Instruction Cycle Time ⁽²⁾	—	4/Fosc	—	—			
3	TosL,	Clock in (OSC1) Low or High	85*	—	—	ns	XT oscillator		
	TosH	Time	20*	—	—	ns	HS oscillator		
			2.0*		—	μS	LP oscillator		
4	TosR,	Clock in (OSC1) Rise or Fall	—	_	25*	ns	XT oscillator		
	TosF	Time	—	—	25*	ns	HS oscillator		
			—	—	50*	ns	LP oscillator		

TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

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13.3 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

DC CH	ARACTE	RISTICS	$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions	
D030	VIL	Input Low Voltage I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	Vss Vss Vss Vss Vss		0.2 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.15 VDD	> > > > >	Pin at hi-impedance RC mode only ⁽³⁾ XT, HS and LP modes	
D040	Vih	Input High Voltage I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	2.0 0.6 VDD 0.85 VDD 0.85 VDD 0.85 VDD 0.85 VDD		VDD VDD VDD VDD VDD VDD	V V V V V	VDD = 3.0V to 5.5V ⁽⁴⁾ Full VDD range ⁽⁴⁾ RC mode only ⁽³⁾ XT, HS and LP modes	
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 Vdd*	_	_	V		
D060	lı∟	Input Leakage Current ^(1,2) I/O ports	-1.0	_	+1.0	μA	For VDD \leq 5.5V: VSS \leq VPIN \leq VDD, pin at hi-impedance	
		MCLR MCLR TOCKI OSC1	-5.0 -3.0 -3.0	 0.5 0.5 0.5		μΑ μΑ μΑ μΑ	$VPIN = VSS + 0.25V$ $VPIN = VDD$ $VSS \le VPIN \le VDD$ $VSS \le VPIN \le VDD,$ $XT, HS and LP modes$	
D080	Vol	Output Low Voltage I/O ports OSC2/CLKOUT		_	0.5 0.5	V V	IOL = 10 mA, VDD = 6.0 V IOL = 1.9 mA, VDD = 6.0 V, RC mode only	
D090	Vон	Output High Voltage ⁽²⁾ I/O ports OSC2/CLKOUT	Vdd – 0.5 Vdd – 0.5	_		V V	IOH = -4.0 mA, VDD = 6.0 V IOH = -0.8 mA, VDD = 6.0 V, RC mode only	

* These parameters are characterized but not tested.

- † Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- **Note 1:** The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.
 - 2: Negative current is defined as coming out of the pin.
 - **3:** For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.
 - 4: The user may use the better of the two specifications.



FIGURE 13-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16CR54A

TABLE 13-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16CR54A

AC Chara	cteristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^\circ C \leq TA \leq +70^\circ C \mbox{ for commercial} \\ -40^\circ C \leq TA \leq +85^\circ C \mbox{ for industrial} \\ -40^\circ C \leq TA \leq +125^\circ C \mbox{ for extended} \end{array} $							
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions		
30	TmcL	MCLR Pulse Width (low)	1.0*	_	_	μS	VDD = 5.0V		
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7.0*	18*	40*	ms	VDD = 5.0V (Comm)		
32	Tdrt	Device Reset Timer Period	7.0*	18*	30*	ms	VDD = 5.0V (Comm)		
34	Tioz	I/O Hi-impedance from MCLR Low	_	_	1.0*	μS			

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C5X

FIGURE 14-2: TYPICAL RC OSC FREQUENCY vs. VDD, CEXT = 20 PF Typical: statistical mean @ 25°C Maximum: mean + 3s (-40°C to 125°C) Minimum: mean – 3s (-40°C to 125°C) 5.5 R = 3.3K5.0 4.5 R = 5K 4.0 3.5 Fosc (MHz) 3.0 R = 10K 2.5 2.0 Measured on DIP Packages, $T = 25^{\circ}C$ 1.5 1.0 R = 100K 0.5 0.0 3.0 3.5 4.0 4.5 5.0 5.5 6.0 VDD (Volts)

FIGURE 14-3:

TYPICAL RC OSC FREQUENCY vs. VDD, CEXT = 100 PF





FIGURE 14-5: TYPICAL IPD vs. VDD, WATCHDOG DISABLED



NOTES:



FIGURE 16-12: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 PF, 25°C)

FIGURE 16-13: MAXIMUM IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 PF, -40°C to +85°C)



NOTES:

17.2 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04E, 20E (Extended) PIC16CR54C/CR56A/CR57C/CR58B-04E, 20E (Extended)

PIC160 PIC160 (Exter	54C/C55/ R54C/CR nded)	A/C56A/C57C/C58B-04E, 20E 56A/CR57C/CR58B-04E, 20E	Standard Operating Conditions (unless otherwise specifie Operating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions	
D001	Vdd	Supply Voltage	3.0 4.5		5.5 5.5	V V	RC, XT, LP, and HS mode from 0 - 10 MHz from 10 - 20 MHz	
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode	
D003	VPOR	VDD start voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset	
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	_	—	V/ms	See Section 5.1 for details on Power-on Reset	
D010	IDD	Supply Current ⁽²⁾ XT and RC ⁽³⁾ modes HS mode	_	1.8 9.0	3.3 20	mA mA	Fosc = 4.0 MHz, Vdd = 5.5V Fosc = 20 MHz, Vdd = 5.5V	
D020	IPD	Power-down Current ⁽²⁾		0.3 10 12 4.8 18 26	17 50* 60* 31* 68* 90*	μΑ μΑ μΑ μΑ μΑ	VDD = 3.0V, WDT disabled VDD = 4.5V, WDT disabled VDD = 5.5V, WDT disabled VDD = 3.0V, WDT enabled VDD = 4.5V, WDT enabled VDD = 5.5V, WDT enabled	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.



FIGURE 17-8: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X, PIC16CR5X

TABLE 17-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X, PIC16CR5X

AC Charac	teristics	$\begin{array}{l} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$							
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions		
30	TmcL	MCLR Pulse Width (low)	1000*		—	ns	VDD = 5.0V		
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)		
32	Tdrt	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)		
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns			

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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28-Lead Plastic Small Outline (SO) - Wide, 300 mil (SOIC)

For the most current package drawings, please see the Microchip Packaging Specification located Note: at http://www.microchip.com/packaging







	Units	INCHES*			MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.050			1.27	
Overall Height	А	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	Е	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	¢	0	4	8	0	4	8
Lead Thickness	С	.009	.011	.013	0.23	0.28	0.33
Lead Width	В	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-013 Drawing No. C04-052

Μ

MCLR Reset	
Register values on2	20
Memory Map	
PIC16C54/CR54/C55	25
PIC16C56/CR56	25
PIC16C57/CR57/C58/CR582	25
Memory Organization	25
MOVF	56
MOVLW	56
MOVWF	57
MPLAB C17 and MPLAB C18 C Compilers	31
MPLAB ICD In-Circuit Debugger	33
MPLAB ICE High Performance Universal In-Circuit Emulat	or
with MPLAB IDE	32
MPLAB Integrated Development Environment Software	31
MPLINK Object Linker/MPLIB Object Librarian	32

Ν

NOP	

0

One Time Dreasemmehle (OTD) Devices	7
One-Time-Programmable (OTP) Devices	
OPTION	57
OPTION Register	
Value on reset	
Oscillator Configurations	
Oscillator Types	
HS	15
LP	
RC	
ХТ	

Ρ

PA0 bit	29
PA1 bit	29
Paging	31
PC	31
Value on reset2	20
PD bit	29
Peripheral Features	. 1
PICDEM 1 Low Cost PIC MCU Demonstration Board6	33
PICDEM 17 Demonstration Board6	64
PICDEM 2 Low Cost PIC16CXX Demonstration Board 6	33
PICDEM 3 Low Cost PIC16CXXX Demonstration Board 6	64
PICSTART Plus Entry Level Development Programmer 6	33
Pin Configurations	. 2
Pinout Description - PIC16C54, PIC16CR54, PIC16C54	6,
PIC16CR56, PIC16C58, PIC16CR58 1	11
Pinout Description - PIC16C55, PIC16C57, PIC16CR57 1	12
PORTA	35
Value on reset2	20
PORTB	35
Value on reset2	20
PORTC	35
Value on reset2	20
Power-Down Mode4	17
Power-On Reset (POR)	21
Register values on2	20
Prescaler4	10
PRO MATE II Universal Device Programmer6	33
Program Counter	31
Program Memory Organization	25
Program Verification/Code Protection4	17

Q

0 avalate (12
Q cycles
Quick-Turnaround-Production (QTP) Devices
R
RC Oscillator17
Read Only Memory (ROM) Devices7
Read-Modify-Write
Register File Map
PIC16C54, PIC16CR54, PIC16C55, PIC16C56,
PIC16CR56
PIC16C57/CR57
PIC16C58/CR5827
Registers
Special Function
Value on reset
Reset
Reset on Brown-Out
RETLW
RLF
RRF

S

evices 7
43, 47, 58
62
43
32
9, 29
20
59
59

Т

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